



Hi-Rel AC/DC PFC MODULE HGMM-150 : 150W POWER

Hi-Rel
Grade ■■

115 VAC Active Power Factor Corrected Variable Frequency 360-800Hz Non Isolated Output Metallic Case



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- AC/DC Non Isolated Power Factor Corrected Module
 - 115 VAC single phase
 - Permanent input range : 95 - 140 VAC
 - Transient input range : 71 - 180 VAC
 - Variable frequency : 360-800Hz
 - MIL-STD-704, ABD100
- Low input current harmonic distorsion < 10%
- Output Power : 150W
- Active inrush current limitation
- Inhibition function
- Leaded process

1- General

The GAIA Converter HGMM-150 designates a family of non isolated AC/DC power factor corrected modules. The HGMM-150 family is designed to be compatible with the latest airborne single phase input bus 115VAC/400Hz for fixed and variable frequency .

The modules accept an AC input voltage ranging from 95Vac to 140Vac and include active power factor that enables a very low level of current harmonic distorsion.

The HGMM-150 is compliant with numerous avionics/military standards requirements among them with :

- the latest Airbus standards ABD100 :
 - permanent input range : 108-122Vac
 - transient : 71Vac/15ms - 180Vac/100ms
 - variable frequency : 360 - 800 Hz
 - power factor : > 0.95
- the international standard DO-160D :
 - permanent input range : 100-122Vac
 - transient : up to 180Vac/100ms
- the US military standard MIL-STD-704E :
 - permanent input range : 108-118Vac
 - transient : 80Vac/10ms - 180Vac/100ms

The HGMM-150 modules include a soft start an active inrush current limitation, a permanent short circuit protection and an inhibit function. The soft-start/active current limitation eliminates inrush current during start-up, the short circuit protection protects the module against short-circuits of any duration by a shut down and restores to normal when the overload is removed.

The HGMM-150 output voltage is set to 375Vdc compatible with GAIA Converter high input voltage series of DC/DC converter and operates with a hold-up capacitance to allows transparency time and ripple reduction.

The design has been carried out with surface mount components and is manufactured in a fully automated process to garranty high quality. Every module is tested with a Gaia Converter automated test equipment. The modules are potted with a bi-component thermal conductive compound and packaged in a metallic case to ensure the module's integrity under high environmental conditions.

2- Product Selection

Single output model : HGMS - 150 - - / -

| Input Voltage Range | Output |
|-------------------------|-------------|
| W : 95-140 VAC / 400 Hz | T : 375 VDC |

Options :
 /T : option for -55°C start up operating temperature
 /S : option for screening and serialization

Suffix :
 -L : leaded process

3- Electrical Specifications

Data are valid at +25°C, unless otherwise specified.

| Parameter | Conditions | Limit or typical | Units | HGMS-150-W-T |
|---|---|---|------------------|----------------------|
| Input | | | | |
| Nominal input voltage | Full temperature range between phase and neutral | Nominal | VAC | 115 |
| Permanent input voltage range (Ui) | Full temperature range between phase and neutral | Min. - Max. | VAC | 95-140 |
| Brown(out input voltage | Full temperature range between phase and neutral | Min. | VAC/s | 90/2 |
| Transient input voltage | Full temperature range between phase and neutral | Minimum Maximum. | VAC/ms VAC/ms | 71/15 180/100 |
| Frequency range permanent (Fi) | Full temperature range Ui min. to max. | Nominal Min. Max. | Hz Hz | 400 360-800 |
| Frequency range transient | Full temperature range Ui min. to max. | Transient compliant with ABD100 | Hz/s | 320/0.3 |
| Power Factor (PF) | Ui nominal Fi nominal | At full load At half load At quarter load | / | 0.99 0.97 0.90 |
| Total Harmonic Distorsion (THD) | Ui min. to max. | from 25% to full load from 360Hz to 800Hz | % | < 10 |
| Individual current harmonic distorsion | Ui min. to max. from Fi min. to max. | 50% to full load | / | see page 3 |
| Start up time | Ui min. to max., Fi nominal with minimum capacitance Co with maximum capacitance Co | Maximum | ms | 30 |
| | | Maximum | ms | 200 |
| Start-up current | Ui nominal, Fi nominal | Maximum peak | A | 8 |
| Current in inhibit mode | Ui nominal, Fi nominal Inhibit | Maximum | mArms | 250 |
| Output | | | | |
| Output voltage | Full temperature range Ui min. to max., full load | Nominal | VDC | 375 |
| Output voltage transient | Input voltage transient Load fast change | Maximum | VDC | 450 |
| Set point accuracy | Ambient temperature : +25°C Ui nominal, 75% load | Maximum | % | +/-3 |
| Output power | Full temperature range Ui min. to max. | Maximum | W | 150 |
| Ripple output voltage | Ui nominal, Fi nominal Full load BW=20MHz | Maximum | Vpp | see curve page 12 |
| Output regulation (Line + load + thermal) | Full temperature range Ui min. to max., Fi nominal No load to full load | Maximum | % | +/-1 |
| Efficiency | Ui nominal, Fi nominal Full load | Typical | % | 90 |
| Admissible capacitive load (Co) | Full temperature range Ui min. to max. | Minimum | μF | 33 |
| | | Maximum | μF | 560 |

3- Electrical Characteristics (continued)

3-1 Power Factor (PF) Characteristics

The Power Factor (PF) is the ratio of the «real» power to the apparent power.

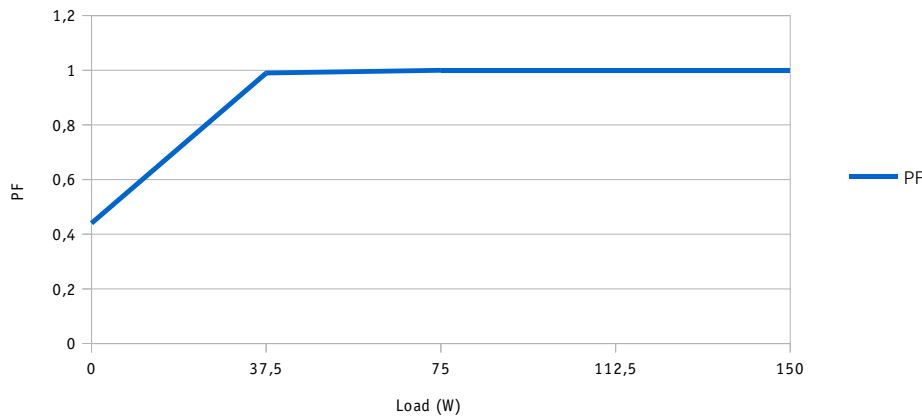
The apparent power is the product of the rms volts measured with one meter and the rms amps measured with another meter (value in VA).

The «real» power is the time average of the instant product of voltage and current (value in Watts).

The «real» power cannot be measured directly with 2 meters as it has to integrate the phase shift between voltage and current. This phase shift between voltage and current reduces the effective power delivered.

The Power Factor (PF) is a measure of the effectiveness with which an AC load can extract the usable power from an AC source.

Power Factor versus Load 115V 400Hz

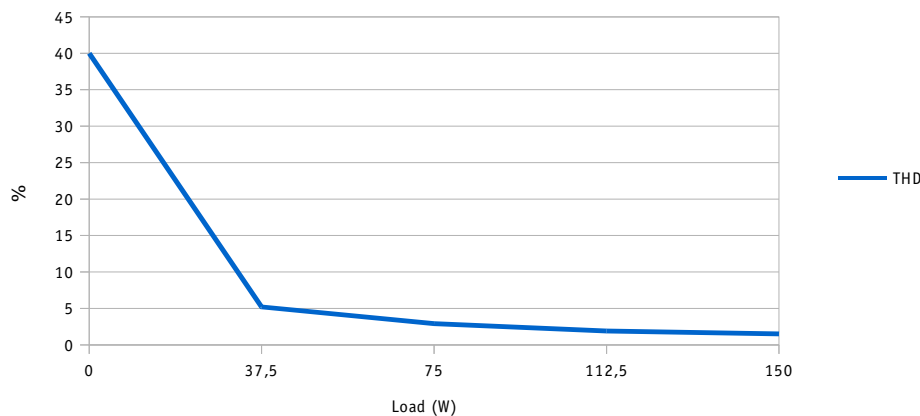


3-2 Total Harmonic Distorsion Factor (THD) Characteristics

The Total Harmonic Distorsion (THD) is the ratio between the total energy contained in all row harmonic (except fundamental harmonic) by the fundamental harmonic wave.

The following curves represent the Total Harmonic Distorsion Factor (THD) for the HGMS-150-W-T at frequency of 400Hz.

Total Harmonic Distorsion (THD) versus Load at 115V 400Hz



3-3 Individual Current Harmonic Distorsion (ICHD) Characteristics

The Individual Current Harmonic Distorsion (ICHD) requirement is a very specific requirement defining for each harmonic row, the maximum admissible current in all functioning conditions.

This requirement induced the Total Harmonic Distorsion Factor (THD) defined above.

These requirements are mainly defined by the aircraft manufacturers in proprietary standards.

GAIA Converter HGMM-150 complies with individual current harmonic distorsion requirements of :

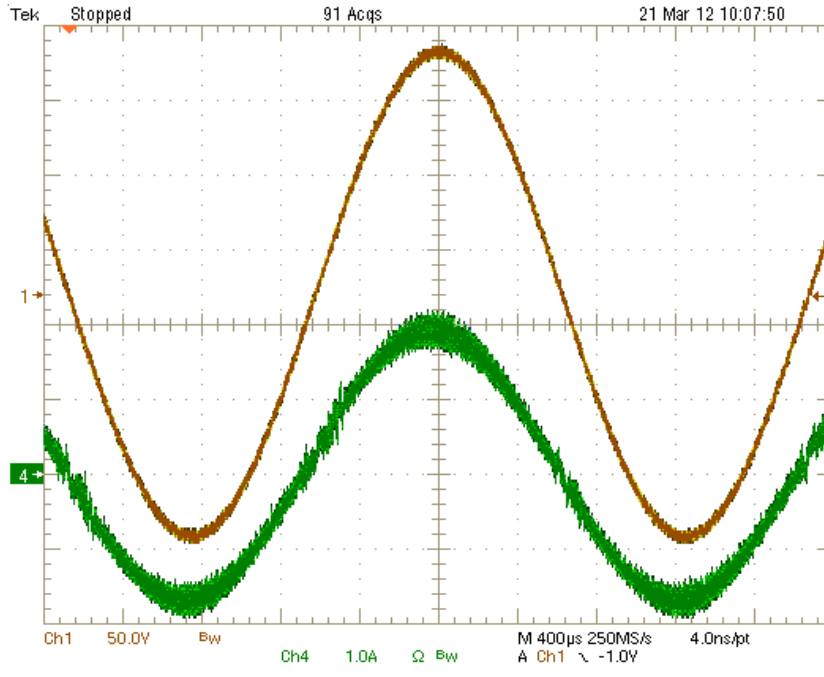
- AIRBUS ABD100 standard section 1.8 and its specific limits on odd non triplen and odd triplen harmonics even 2 & 4 and other even harmonics.
- BOEING D6-44588 and its specific limits on odd non triplen and odd triplen harmonics even harmonics.
- Various other standards : AIRBUS AMD24, MIL-STD-1399

3- Electrical Characteristics (continued)

3-4 Anharmonic Input Current

The anharmonic input current of the HGMS-150-W-T is given hereafter at 400Hz for 150W power.

Anharmonic Input Current at 400Hz for HGMS-150-W-T

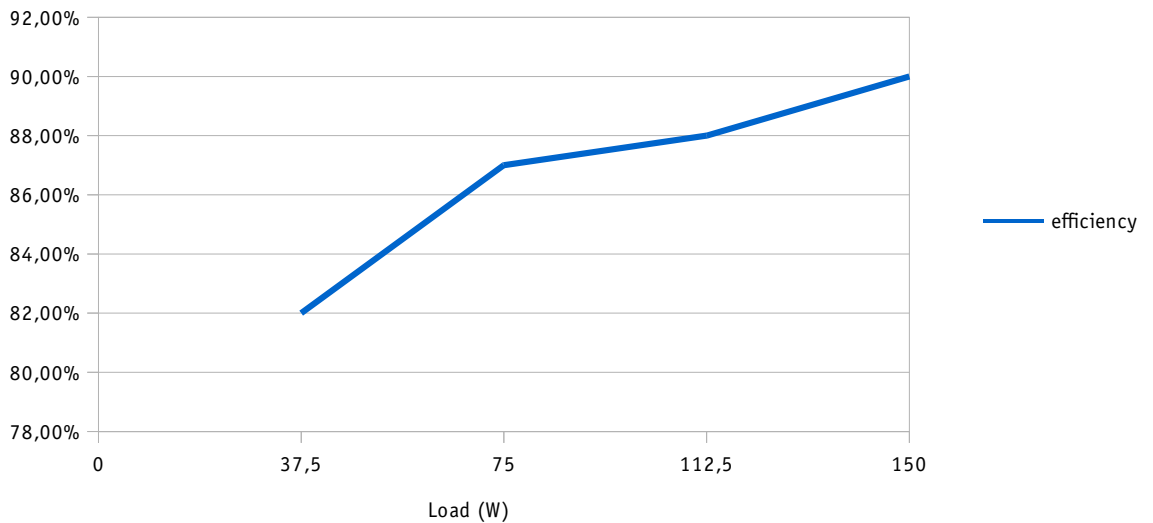


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3-5 Efficiency

The efficiency curve of the HGMS-150-W-T is given hereafter :

Efficiency vs Load at 115V 400Hz



4- Switching Frequency

| Parameter | Conditions | Limit or typical | Specifications |
|---------------------|---|------------------|----------------|
| Switching frequency | Full temperature range Ui min. to max. No load to full load | Nominal, fixed | 250 KHz |

5- Isolation

| Parameter | Conditions | Limit or typical | Specifications |
|--------------------------------|-----------------|------------------|-------------------|
| Electric strength test voltage | Input to output | Minimum | No isolation |
| | Pin to case | Minimum | 2.200 VDC / 1 min |

6- Protection Functions

| Characteristics | Protection Device | Recovery | Limit or typical | Specifications |
|---------------------------------------|--------------------------------------|--------------------|------------------|----------------|
| Output short circuit protection (SCP) | Hiccup circuitry with auto-recovery | Automatic recovery | Permanent | See section 11 |
| Output over power protection (OPP) | | Automatic recovery | Typical | 200W |
| Over temperature protection (OTP) | Thermal device with hysteresis cycle | Automatic recovery | Maximum | 115°C |

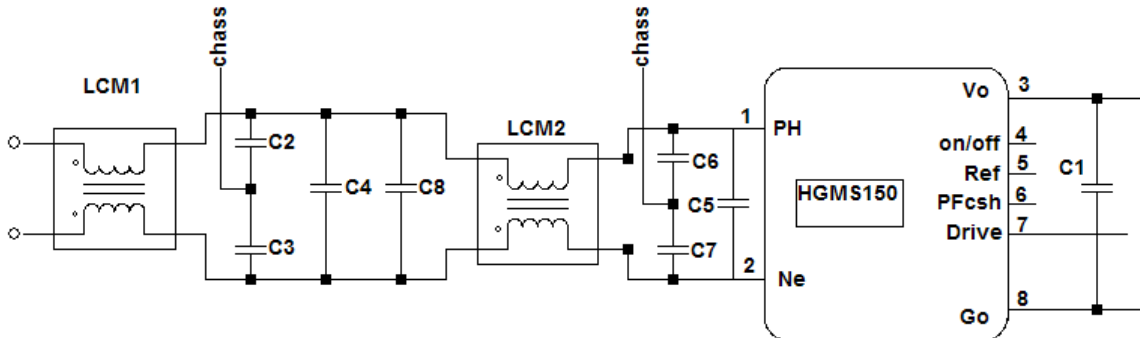
7- Reliability Data

| Characteristics | Conditions | Temperature | Specifications |
|--|-------------------------------------|------------------------------|----------------------------|
| Mean Time Between Failure (MTBF) According to MIL-HDBK-217F | Ground fixed (Gf) | Case at 40°C Case at 85°C | |
| | Airborne, Inhabited, Cargo (AIC) | Case at 40°C Case at 85°C | 400 000 Hrs 143 000 Hrs |
| Mean Time Between Failure (MTBF) According to IEC-62380-TR | Avionics Military Cargo | / | Consult factory |

8- Electromagnetic Interference

Electromagnetic interference requirements according to DO-160D or MIL-STD-461D/E can be easily achieved as indicated in the following table with the use of an additional external filter as described hereafter.

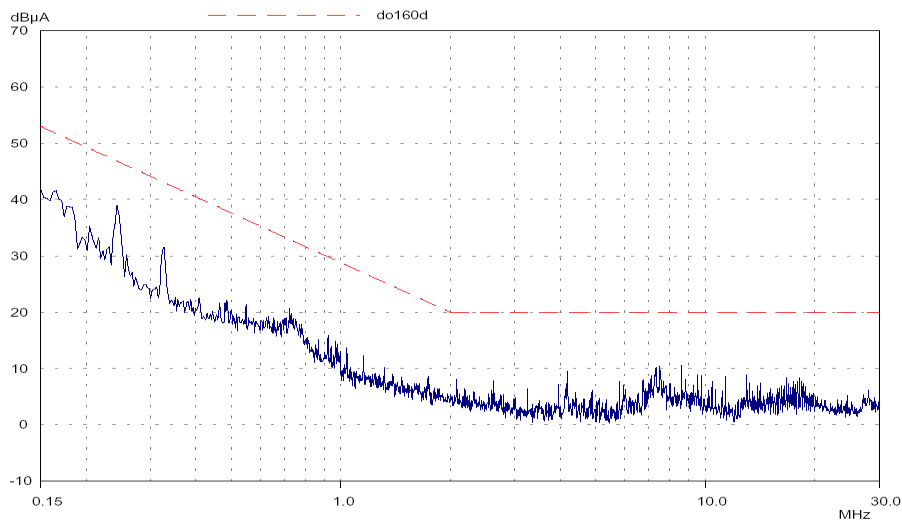
| Standards | DO-160D | MIL-STD-461E | Compliance |
|---|------------|------------------|--|
| Conducted emission (CE) : Low frequency High frequency | Section 21 | CE 101 CE 102 | compliant module stand alone compliant with additional filter |
| Conducted susceptibility (CS) : Low frequency High frequency | Section 20 | CS 101 CS114 | compliant with additional filter compliant with additional filter |
| Radiated emission (RE) : Magnetic field Electrical field | Section 21 | RE 101 RE 102 | compliant module stand alone compliant module stand alone |
| Radiated susceptibility (RS) : Magnetic field Electrical field | Section 20 | RS 101 RS 013 | compliant module stand alone compliant module stand alone |



Recommended list of components :

- LMC1, LMC2 : Common mode choke 5 to 7mH (Würth Elektronik : 744834407)
- C2, C3, C6, C7..... : Ceramic chip capacitors 2.2 nF/2Kv 1210 (example AVX : 1210GC222MAT)
- C4,C5 : Film chip capacitor 330 nF/250V (example AVX : CB177K0154K)
- C8 : Ceramic chip capacitor 100 nF/500V (example Syfer : 1812J50000104MX)
- C1 : Cf section 13-1

Fig : DO-160D Conducted Noise Emission



9- Thermal Characteristics

| Characteristics | Conditions | Limit or typical | Performances |
|-------------------------------------|--|--------------------|---------------------|
| Operating ambient temperature range | Ambient temperature | Minimum Maximum | - 40°C see below |
| Operating case temperature range | Case temperature | Minimum Maximum | - 40°C + 105°C |
| Storage temperature range | Non functioning | Minimum Maximum | - 55°C + 125°C |
| Thermal resistance | Rth case to ambient in free air natural convection | Typical | 8°C/W |

The following discussion will help designer to determine the thermal characteristics and the operating temperature.

The HGMM-150 series maximum **baseplate** temperature at full load must not exceed 105°C. Heat can be removed from the baseplate via three basic mechanisms :

- Radiation transfert : radiation is counting for less than 5% of total heat transfert in majority of case, for this reason the presence of radiant cooling is used as a safety margin and is not considered.
- Conduction transfert : in most of the applications, heat will be conducted from the baseplate into an attached heatsink or heat conducting member; heat is conducted thru the interface.
- Convection transfert : convecting heat transfer into air refers to still air or forced air cooling.

In majority of the applications, heat will be removed from the baseplate either with :

- heatsink,
- forced air cooling,
- both heatsink and forced air cooling.

To calculate a maximum admissible ambient temperature the following method can be used.

Knowing the maximum baseplate temperature $T_{base} = 105^{\circ}\text{C}$ of the module, the power used P_{out} and the efficiency η :

- determine the power dissipated by the module P_{diss} that should be evacuated :

$$P_{diss} = P_{out}(1/\eta - 1) \quad (A)$$

- determine the maximum ambient temperature :

$$T_a = 105^{\circ}\text{C} - R_{th}(b-a) \times P_{diss} \quad (B)$$

where **$R_{th}(b-a)$** is the thermal resistance from the baseplate to ambient.

This thermal $R_{th}(b-a)$ resistance is the summ of :

- **the thermal resistance of baseplate to heatsink ($R_{th}(b-h)$)**. The interface between baseplate and heatsink can be nothing or a conducting member, a thermal compound, a thermal pad.... The value of $R_{th}(b-h)$ can range from 0.4°C/W for no interface down to 0.1°C/W for a thermal conductive member interface.
- **the thermal resistance of heatsink to ambient air ($R_{th}(h-a)$)**, which is depending of air flow and given by heatsink supplier.

The table hereafter gives some example of thermal resistance for different heat transfert configurations.

| Heat transfert | Thermal resistance heatsink to air $R_{th}(h-a)$ | Thermal resistance baseplate to heatsink $R_{th}(b-h)$ | Global resistance |
|-----------------------------|--|--|-------------------|
| Free air cooling only | No Heatsink baseplate only : 8°C/W | No need of thermal pad | 8°C/W |
| | Heatsink Thermalloy 242209B93600G : 3,8°C/W | Bergquist Silpad* : 0,14°C/W | 3,94°C/W |
| | Heatsink Fischer Elektronik SK DC 5159SA : 3,8°C/W | Bergquist Silpad* : 0,14°C/W | 3,94°C/W |
| Forced air cooling 200 LFM | No Heatsink baseplate only : 4,5°C/W | No need of thermal pad | 4,5°C/W |
| | Heatsink Thermalloy 242209B93600 : 2°C/W | Bergquist Silpad* : 0,14°C/W | 2,14°C/W |
| | Heatsink Fischer Elektronik SK DC 5159SA : 2,5°C/W | Bergquist Silpad* : 0,14°C/W | 2,64°C/W |
| Forced air cooling 400 LFM | No Heatsink baseplate only : 3,2°C/W | No need of thermal pad | 3,2°C/W |
| | Heatsink Thermalloy 242209B93600 : 1,25°C/W | Bergquist Silpad* : 0,14°C/W | 1,39°C/W |
| | Heatsink Fischer Elektronik SK DC 5159SA : 1,7°C/W | Bergquist Silpad* : 0,14°C/W | 1,84°C/W |
| Forced air cooling 1000 LFM | No Heatsink baseplate only : 1,7°C/W | No need of thermal pad | 1,7°C/W |
| | Heatsink Fischer Elektronik SK DC 5159SA : 0,9°C/W | Bergquist Silpad* : 0,14°C/W | 1,04°C/W |

Fischer Elektronik and Thermalloy are heatsink manufacturers. «Silpad»[®] is a registered trademark of Bergquist.

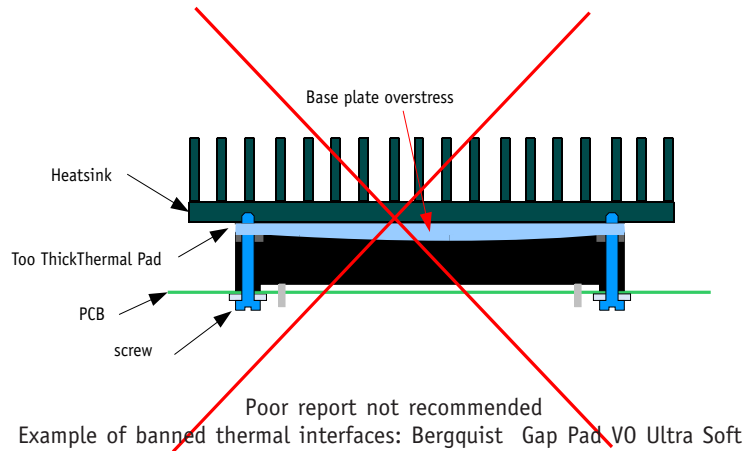
Note* : Silpad performance are for Silpad 400 with pressure conditions of 50 Psi. Surface of HGMM-350 series is 5,5 inch².

9- Thermal Characteristics (continued) : Heatsink Mounting

To mount properly the module to heatsink, some important recommendations need to be taken into account in order to avoid overstressing conditions that may lead to premature failures.

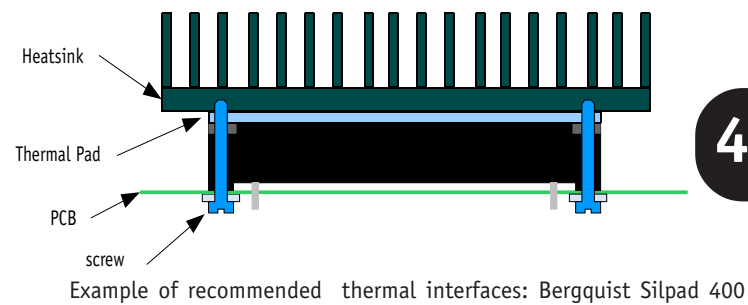
The module case is built with a copper IMS (isolated metallic substrate) crimped on an aluminum frame that provides case rigidity. The IMS surface is the module base plate that need to be reported to heat sink to achieve proper cooling. If for some reasons like poor module report, the IMS base plate is subject to mechanical overstress, module's electrical characteristics may be definitely affected.

A typical example of damageable report is the use of thick thermal interface with usual screwing torque applied on mounting screws. This combination causes a high pressure on baseplate center due to thermal interface material compression. The final consequence is a slight IMS bending that can conduct for the module to fail high voltage isolation leading to heavy electrical damage on internal circuit.



The good practice is to respect the 4 following recommendations:

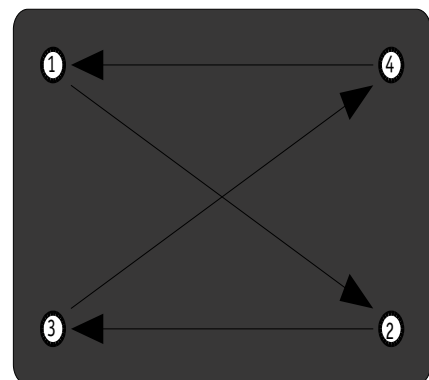
- do not exceed recommended screwing torque of 0.7 N.m
- prefer thin thermal pad with thickness lower than 0.015" (0,34 mm).
- GAIA Converter recommends to use thin thermal pads instead of thermal compound like grease.
- take care to reflow module leads only when all assembly operations are completed.
- do not report module on surfaces with poor flatness characteristics. GAIA Converter recommends not to overflow 0,1mm/m for the surface flatness.



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Gaia converter suggests to follow the procedure hereunder for the mechanical assembly procedure in order to avoid any stress on the pins of the converters. It is good practice to be sure to mount the converters first mechanically, then solder the units in place.

1. Choice of the thermal gap pad : its shape must be the same as the module. The dimensions of the gap pad can be a little larger than the module.
2. Screw the converter to the heatsink and/or to the board. The four screws have to be screwed in a "X" sequence.
 - Lightly finger-tighten all screws and run several «X» sequences before achieving final torque to get homogeneous tightening.
 - Torque screws from 3 in.lbs (0.35 N.m). to 6 in.lbs (0.7 N.m)
3. Screw the heatsink to the board.
4. Solder the pins of the converters on the board. This sequence avoids mechanical stresses on the converters that could lead to stress internal components or assemblies and cause their failures.



10- Environmental Qualifications

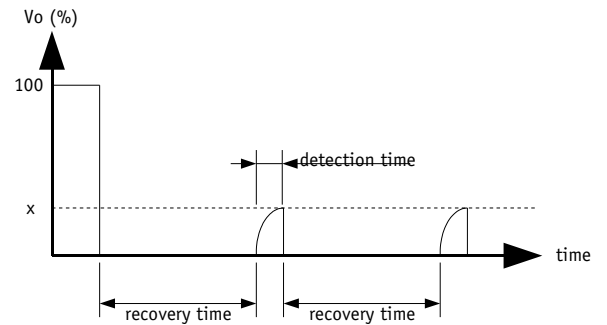
The modules have been subjected to the following environmental qualifications.

| Characteristics | Conditions | Severity | Test procedure |
|----------------------------------|---|---|------------------------------|
| Climatic Qualifications | | | |
| Life at high temperature | Duration Temperature / status of unit | Test D : 1.000 Hrs @ 105°C case, unit operating @ 125°C ambient, unit not operating | MIL-STD-202G Method 108A |
| Altitude | Altitude level C Duration Climb up Stabilization Status of unit | 40.000 ft@-55°C 30 min. 1.000 ft/min to 70.000 f@-55°C, 30 min. unit operating | MIL-STD-810E Method 500.3 |
| Humidity cyclic | Number of cycle Cycle duration Relative humidity variation Temperature variation Status of unit | 10 Cycle I : 24 Hrs 60 % to 88 % 31°C to 41°C unit not operating | MIL-STD-810E Method 507.3 |
| Humidity steady | Damp heat Temperature Duration Status of unit | 93 % relative humidity 40°C 56 days unit not operating | MIL-STD-202G Method 103B |
| Salt atmosphere | Temperature Concentration NaCl Duration Status of unit | 35°C 5 % 48 Hrs unit not operating | MIL-STD-810E Method 509.3 |
| Temperature cycling | Number of cycles Temperature change Transfert time Steady state time Status of unit | 200 -40°C / +85°C 40 min. 20 min. unit operating | MIL-STD-202A Method 102A |
| Temperature shock | Number of shocks Temperature change Transfert time Steady state time Status of unit | 100 -55°C / +105°C 10 sec. 20 min. unit not operating | MIL-STD-202G Method 107G |
| Mechanical Qualifications | | | |
| Vibration (Sinusoidal) | Number of cycles Frequency / amplitude Frequency / acceleration Duration Status of unit | 10 cycles in each axis 10 to 60 Hz / 0.7 mm 60 to 2000 Hz / 10 g 2h 30 min. per axis unit not operating | MIL-STD-810D Method 514.3 |
| Shock (Half sinus) | Number of shocks Peak acceleration Duration Shock form Status of unit | 3 shocks in each axis 100 g 6 ms 1/2 sinusoidal unit not operating | MIL-STD-810D Method 516.3 |
| Bump (Half sinus) | Number of bumps Peak acceleration Duration Status of unit | 2000 Bumps in each axis 40 g 6 ms unit not operating | MIL-STD-810D Method 516.3 |

11- Description of Protections

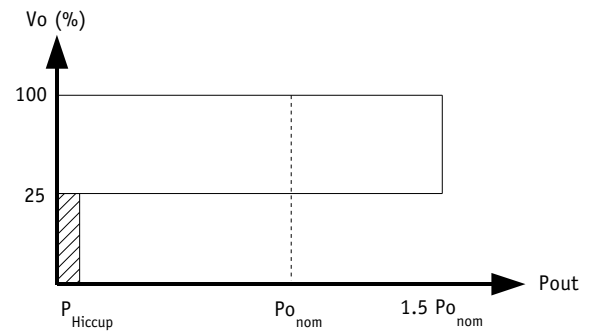
11-1 Output Short Circuit Protection (SCP)

The short circuit protection device protects the module against short circuits of any duration. It operates in «hiccup» mode by testing approximately every «recovery time» (typically 1.1s) if an overload is applied with a detection time lower than 70ms and restores the module to normal operation when the short circuit is removed.



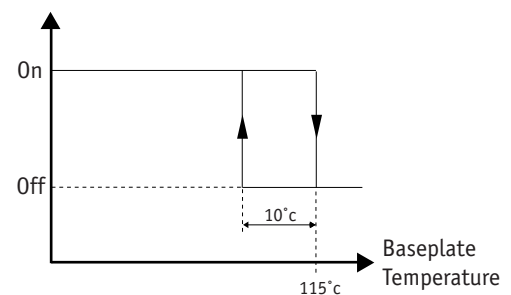
11-2 Output Over Power Protection (OPP)

The HGMM-150 incorporates a foldback power limit and protection circuit. When the output power reaches 1.5 times its full-rated power, the output voltage falls along the foldback line as described in the figure herein. When the output voltage decreases below 40% of V_{Onom} the module falls in a hiccup mode and activates the short circuit protection. The module restarts automatically to normal operation when overcurrent is removed.



11-3 Over Temperature Protection (OTP)

A thermal protection device adjusted at 115°C ($\pm 5\%$) internal temperature with 10°C hysteresis cycle will inhibit the module as long as the overheat is present and restores to normal operation automatically when overheat is removed. The efficiency of the OTP function is warranty with the module mounted on a heatsink.



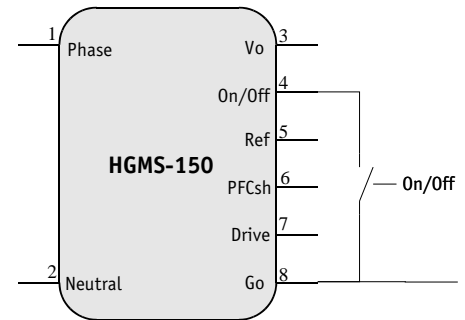
12- Description of Functions

12-1 On/Off Function

The control pin 4 (On/Off) can be used for applications requiring On/Off operation. This may be done with an open collector transistor, a switch, a relay or an optocoupler.

- The converter is disabled by pulling low the pin 4.
- No connection or high impedance on pin 4 enables the converter.

By releasing the On/Off function, the converter will restart within the start up time specifications given in table section 4.



| Parameter | Unit | Min. | Typ. | Max. | Notes, conditions |
|-------------------------------|------|------|------|------|-------------------|
| On/Off module enable voltage | Vdc | 2,35 | / | 5,5 | |
| On/Off module disable voltage | Vdc | 0 | / | 2,35 | |
| On/Off module enable delay | ms | / | / | / | See start-up time |
| On/Off module disable delay | µs | / | / | 100 | Vin, full load |

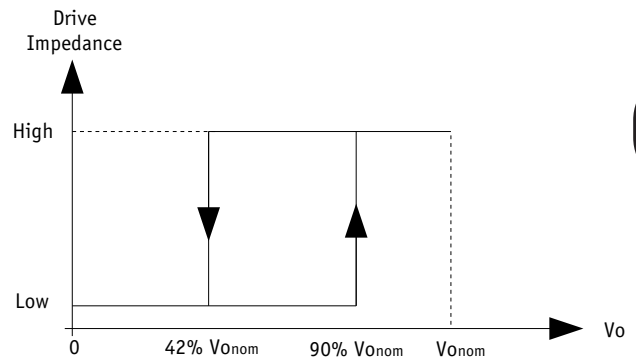
12-2 «Drive» Function

The HGMM-150 with its 375Vdc output has to be used in conjunction with a hold-up capacitor and a companion isolated module MGDM-150-T series of GAIA Converter.

The drive function is a signal that controls the start-up and the stop of the the companion module.

At start-up of the HGMM-150, the drive function is in low impedance status preventing the companion module to start as long as the hold-up capacitor is not charged to reach 375Vdc.

When the capacitor reaches 90% of its charge, the drive signal is released allowing the companion module to start-up. If the HGMM-150 is powered-down in case of input bus failure for example, the hold-up capacitor will discharge to maintain the companion module in operation down to a voltage of 150Vdc then the drive signal will stop the companion module to operate with a low impedance signal.



| Parameter | Unit | Min. | Max. | Notes, conditions |
|-------------------|------------|------|------|-------------------|
| Enable threshold | % of VOnom | 89% | 93% | / |
| Disable threshold | % of VOnom | 39% | 44% | / |

12-3 «REF» Function

The signal «REF» is an auxiliary voltage of 7.5Vdc +/-2% referenced to Go. It can provide a maximum current of 1.5mA. It is recommended to add a 100nF decoupling capacitor when this signal is used. When the module is turned off or when there is an input power interruption, the signal Vref drops to 0Vdc.

13- Application Notes

13-1 Connections

The HGMM-150 has to be used in conjunction with an external hold-up capacitor across the outputs to limit the output voltage ripple.

This capacitor has to be carefully chosen to avoid damaging the HGMM-150.

A low ESR capacitor is recommended; as this ESR increases with temperature the following ratings should apply :

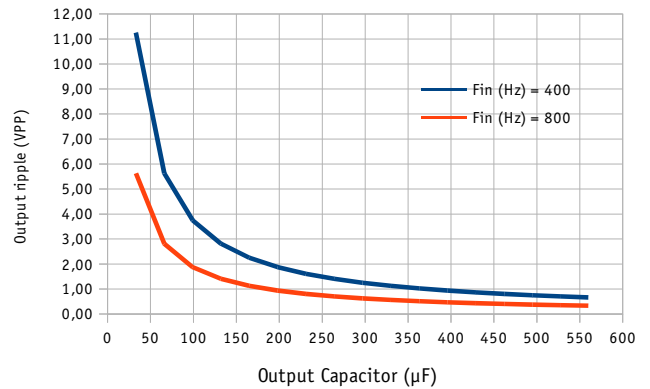
- max ESR @ 20°C : 1 Ohm
- max ESR @ -40°C : 5 Ohm

The capacitor voltage rating has to be chosen according to the maximum permanent & transient output voltage specified.

The charts hereby specify for a given capacitance value the resultant output ripple value.
Maximum capacitor value range is given in table section 3.

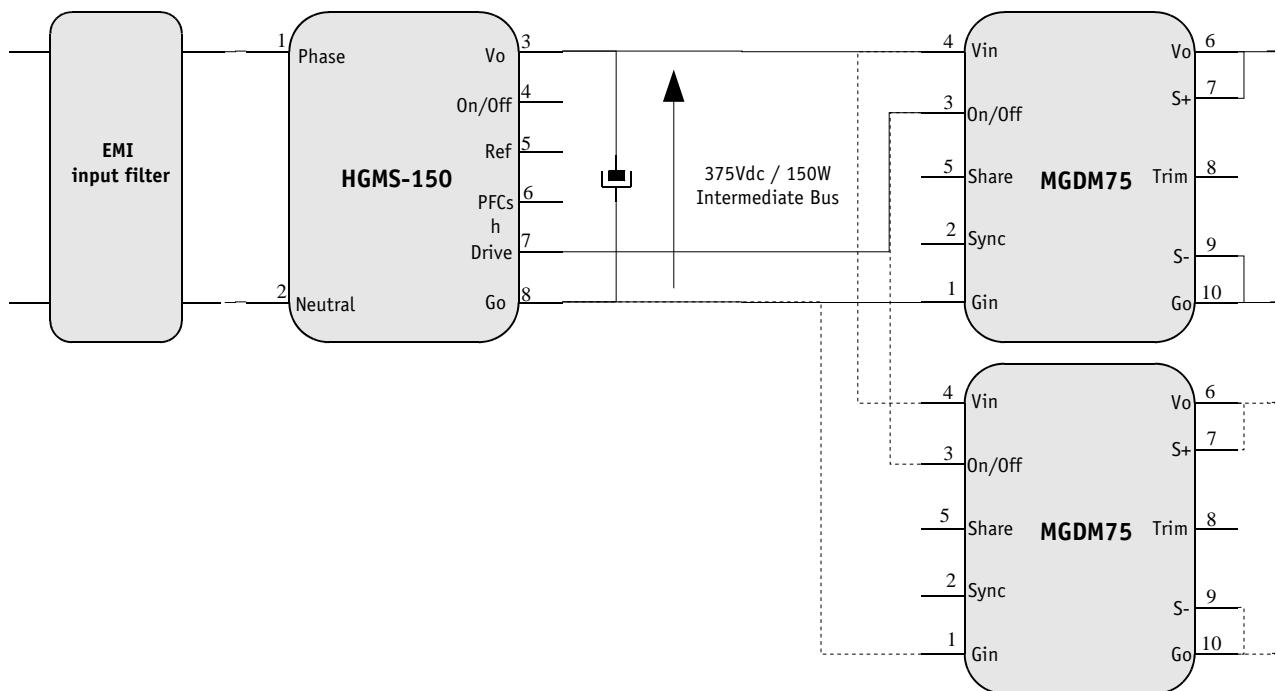
This capacitor is also used to achieve hold-up function for transparency time.

Output Ripple vs Output Capacitor for HGMS-150-W-T



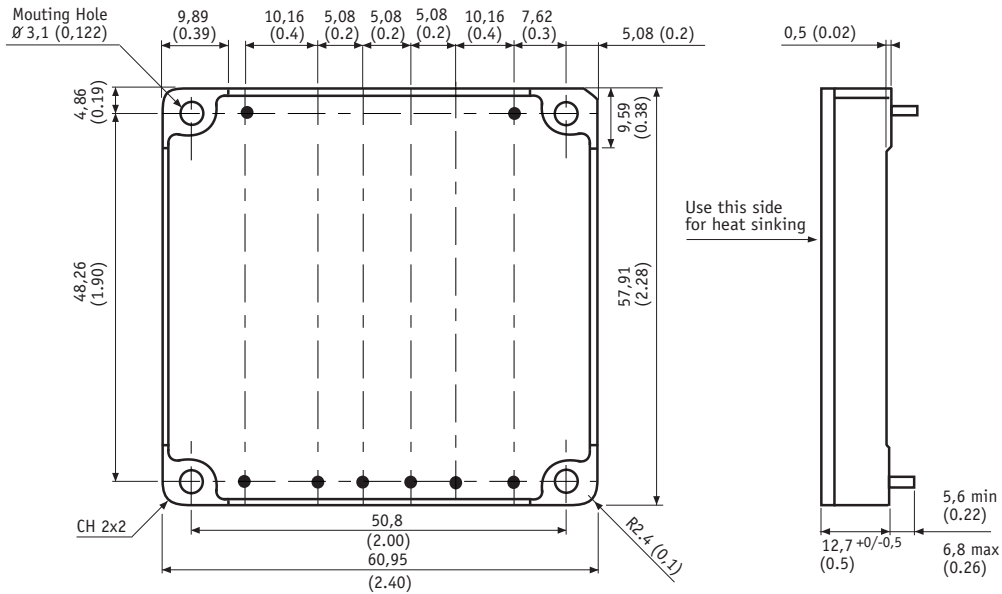
The HGMM-150 output voltage is a high and non isolated voltage of 375 Vdc.

To achieve usual low voltages such as 5, 15 or 28 Vdc, the HGMS-150 module has to be connected with a GAIA Converter compatible companion module. Companion modules can be found among all the high input series i.e with 120V-480V input range down to low voltage as shown in the figure below.



14- Dimensions

Dimension are given in mm (inches). Tolerance : +/- 0,2 mm (+/- 0.01 ") unless otherwise indicated.
Weight : 110 grams (4.30 Ozs) max.



Pin dimensions : Ø 1 mm (0.04")

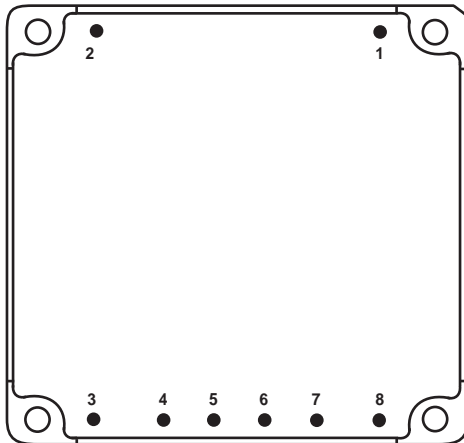
15- Materials

Frame : Aluminium alodined coating.
Baseplate : Copper with tin finishing.
Pins : Plated with pure matte tin over nickel underplate.

16- Product Marking

Side face : Company logo.
: Module reference : HGMS-150-»X»-»Y».
Date code : year and week of manufacturing, suffix, /option.

17- Connections



Bottom view

| Pin | Single output |
|-----|----------------|
| 1 | Phase |
| 2 | Neutral |
| 3 | Output (Vo) |
| 4 | On/Off |
| 5 | Ref |
| 6 | Do not connect |
| 7 | Drive |
| 8 | Common (Go) |



For more detailed specifications and applications information, contact :

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